

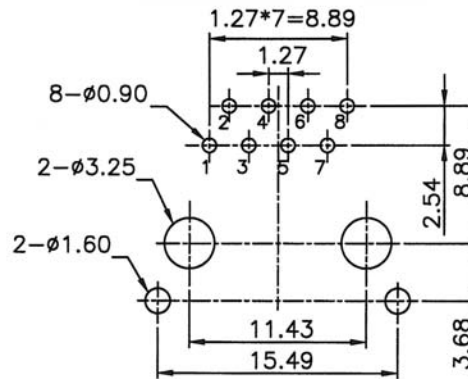
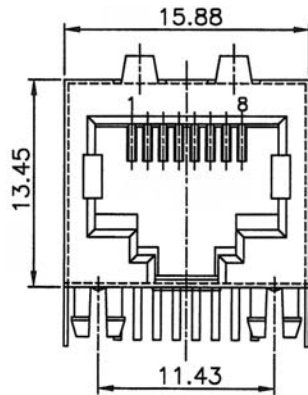
SIDE ENTRY MODULAR PCB JACK 8P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

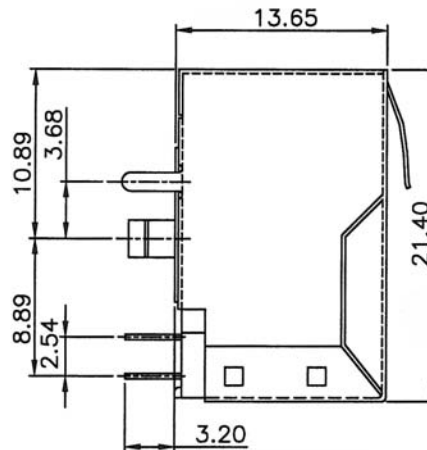
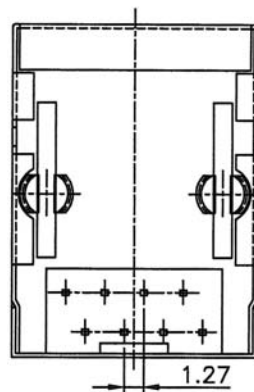
Insulation Resistance: 500MΩ Min.
Contact Resistance: 20mΩ Max.
Rating Current: 1.5A Max.
Rating Voltage: 120V AC.
Dielectric Voltage: 1000 Vrms 60 Sec. Min.
Temperature Range: -40°C / +85°C
Durability: 500 Mating cycles Min.

MATERIALS

Housing: PBT Glass Filled (UL 94V-0)
Soldering Temperature: 235°C
Color: Black
Spring Wire: Phosphor Bronze
 Gold plating Over Nickel
Shield: Brass plating Nickel Alloy
All materials must be RoHS compliant.



Recommended P.C. Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N M J $\frac{x x}{1} - \frac{x x x}{2 3} B$

1. CATEGORY TYPE:
 "5N" CAT. 3
 "V2" CAT. 5
2. NO. OF POSITIONS & CONTACTS:
 "88" 8P8C
 "84" 8P4C
3. CONTACT FINISH:
 "A" 6 MICROINCH GOLD
 "B" 15 MICROINCH GOLD
 "C" 30 MICROINCH GOLD
 "D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG

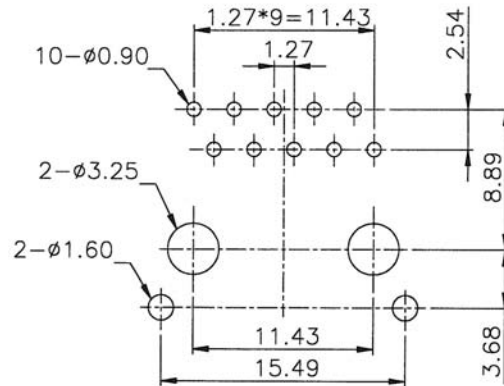
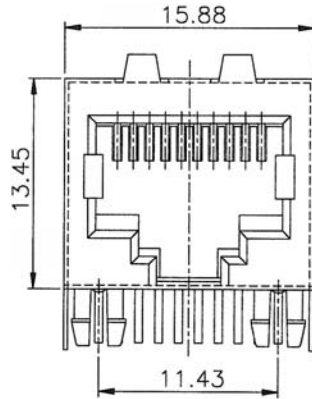
SIDE ENTRY MODULAR PCB JACK 10P PROFILE=13.65MM (FULLY SHIELDED)

SPECIFICATIONS

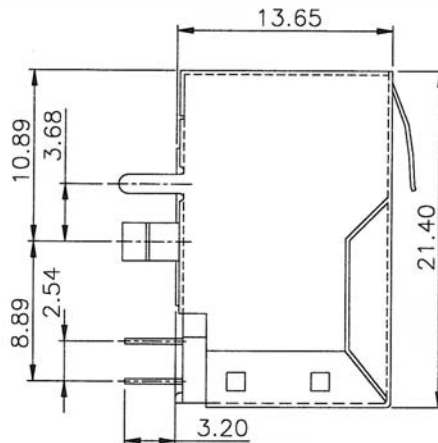
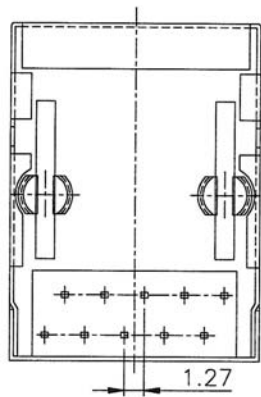
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Recommended P.C.Board Layout
(TOP VIEW)



ORDERING INFORMATION:

P/N MJ5N - $\frac{00}{T} \times \frac{B}{2}$

1. NO. OF POSITIONS & CONTACTS:
"00" 10P10C
2. CONTACT FINISH:
"A" 6 MICROINCH GOLD
"B" 15 MICROINCH GOLD
"C" 30 MICROINCH GOLD
"D" 50 MICROINCH GOLD

NOTE: GROUNDING PIN SPACING=3.68MM BEFORE PEG